



Material Content Data Sheet



Sales Product Name		IPB039N10N3 G		Issued		29. August 2013		
MA#		MA000801654						
Package		PG-TO263-7-3		Weight*		1526.93 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	8.861	0.58	0.58	5803	5803
leadframe	non noble metal	iron	7439-89-6	0.909	0.06		595	
	inorganic material	phosphorus	7723-14-0	0.273	0.02		179	
	non noble metal	copper	7440-50-8	907.924	59.44	59.52	594609	595383
wire	non noble metal	aluminium	7429-90-5	12.909	0.85	0.85	8454	8454
encapsulation	organic material	carbon black	1333-86-4	8.661	0.57		5672	
	plastics	epoxy resin	-	95.267	6.24		62391	
	inorganic material	silicondioxide	60676-86-0	473.449	31.01	37.82	310067	378130
leadfinish	non noble metal	tin	7440-31-5	12.317	0.81	0.81	8066	8066
plating	non noble metal	nickel	7440-02-0	0.269	0.02		176	
	inorganic material	phosphorus	7723-14-0	0.001	0.00	0.02	0	176
solder	noble metal	silver	7440-22-4	0.152	0.01		100	
	non noble metal	tin	7440-31-5	0.122	0.01		80	
	non noble metal	lead	7439-92-1	5.815	0.38	0.40	3808	3988
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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